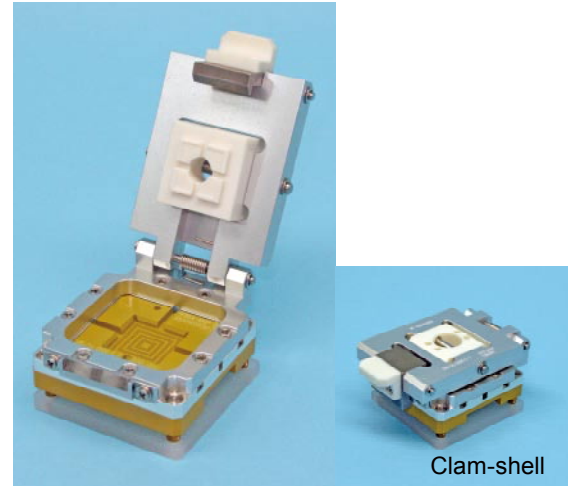


Clip-on setup



Clam-shell

BGA / LGA / QFN Test Socket

Applications

- BGA / LGA / QFN package function test.
- BGA / LGA / QFN package burn-in test.

Features

- Adopting high performance, high durability and high reliability contact probe.
- Contact probes can be removed one by one, enabling the user to perform a maintenance.
- Wide range of probe variations, (from 0.3mm to 1.27mm pitch)
- Incorporating standard contact probes make the custom socket design available.
- Available to test wafer level CSP test and prototype IC.

Specifications

Socket Design	Open-top, Clam-shell, Clip-on setup
Pitch	0.3mm ~ 1.27mm
Operating Temperature	- 55°C ~ +125°C(+150°C)*
Fabrication	Molded or Milling
Material	Super engineering plastic

* Customized for 150°C case